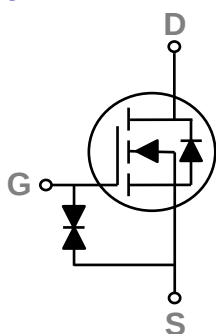


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

PPAK3X3 Pin Configuration



BVDSS	RDS(ON)	ID
100V	38mΩ	16A

Features

- 100V,16A, $R_{DS(ON)} = 38m\Omega$ @ $V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available
- ESD Protection Diode Embedded

Applications

- Networking
- Load Switch
- LED applications

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	16	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	10	A
I_{DM}	Drain Current – Pulsed ¹	64	A
EAS	Single Pulse Avalanche Energy ²	20	mJ
IAS	Single Pulse Avalanche Current ²	20	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	29.5	W
	Power Dissipation – Derate above 25°C	0.24	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	4.24	$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=100V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=80V, V_{GS}=0V, T_J=85^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 20	μA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=10A$	---	32	38	$m\Omega$
		$V_{GS}=4.5V, I_D=8A$	---	46	60	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.5	V

Dynamic and switching Characteristics³

Q_g	Total Gate Charge	$V_{DS}=50V, V_{GS}=10V, I_D=7A$	---	7	14	nC
			---	4	8	
Q_{gs}	Gate-Source Charge	$V_{DS}=50V, V_{GS}=4.5V, I_D=7A$	---	0.7	1.5	
Q_{gd}	Gate-Drain Charge		---	2	4	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=50V, V_{GS}=10V, R_G=6\Omega$ $I_D=7A$	---	6	12	ns
T_r	Rise Time		---	10	20	
$T_{d(off)}$	Turn-Off Delay Time		---	20	40	
T_f	Fall Time		---	13	25	
C_{iss}	Input Capacitance	$V_{DS}=50V, V_{GS}=0V, F=1\text{MHz}$	---	360	700	pF
C_{oss}	Output Capacitance		---	80	150	
C_{rss}	Reverse Transfer Capacitance		---	6	12	
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	---	0.4	---	Ω

Guaranteed Avalanche Energy

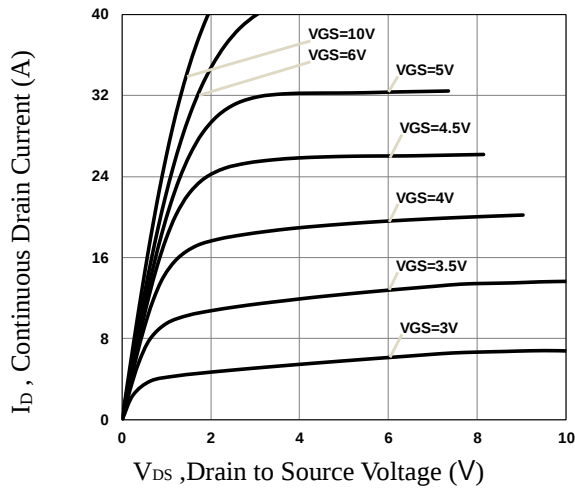
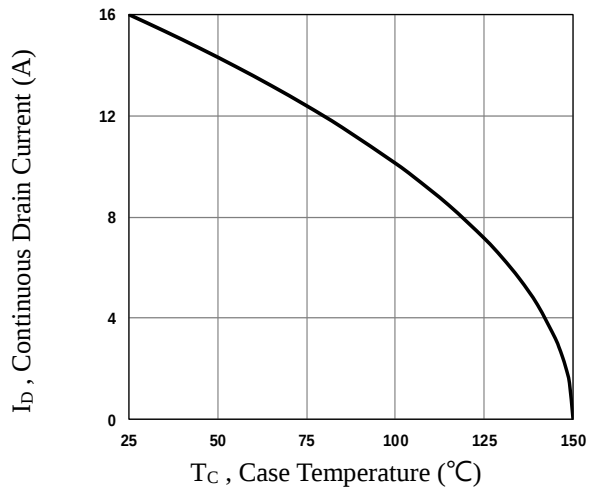
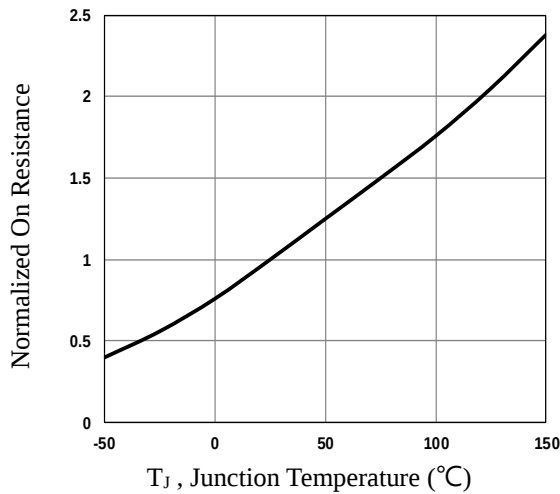
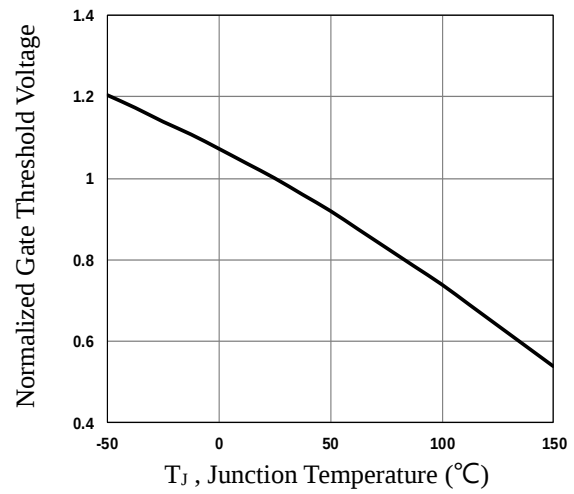
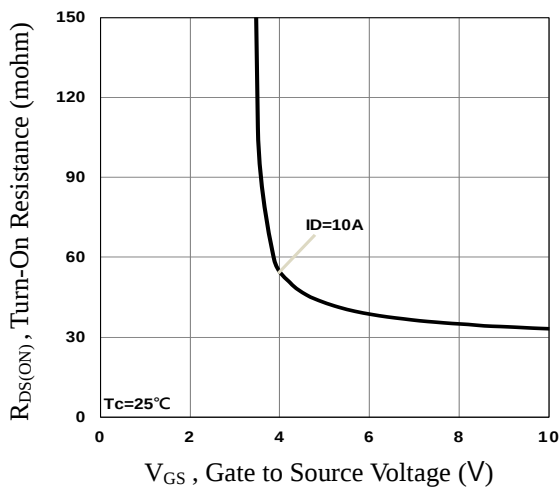
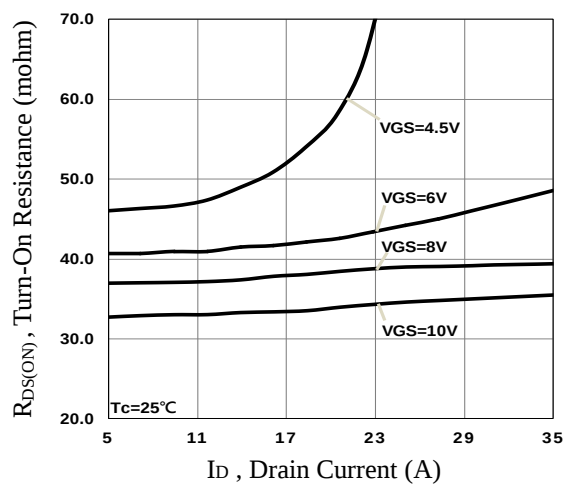
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy	$V_{DD}=50V, L=0.1mH, I_{AS}=14A$	9.8	---	---	mJ

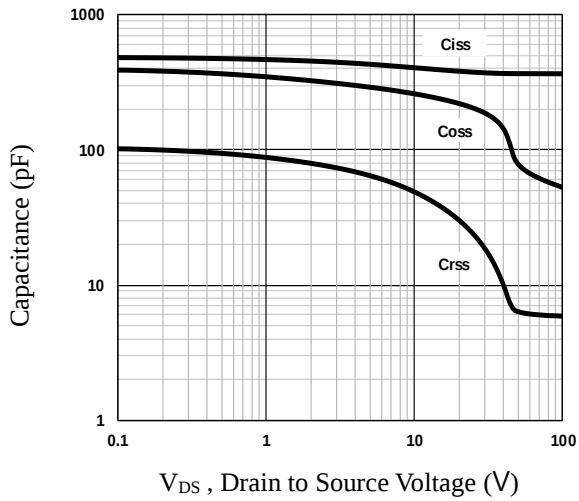
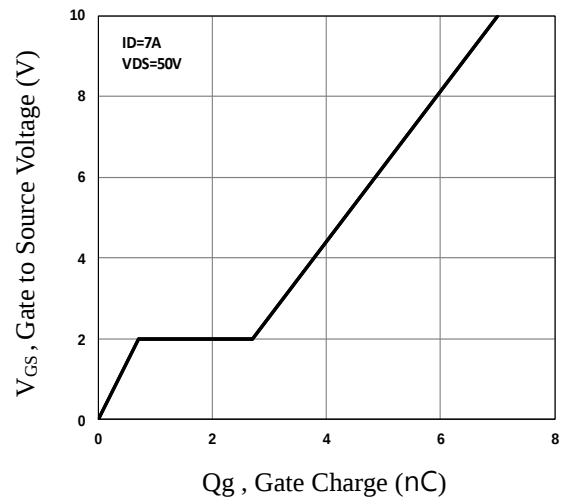
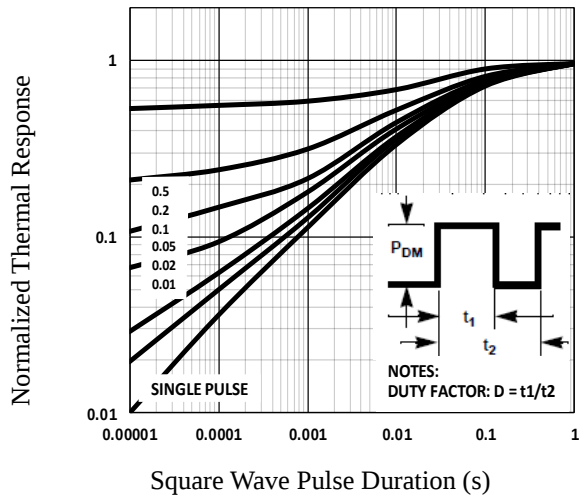
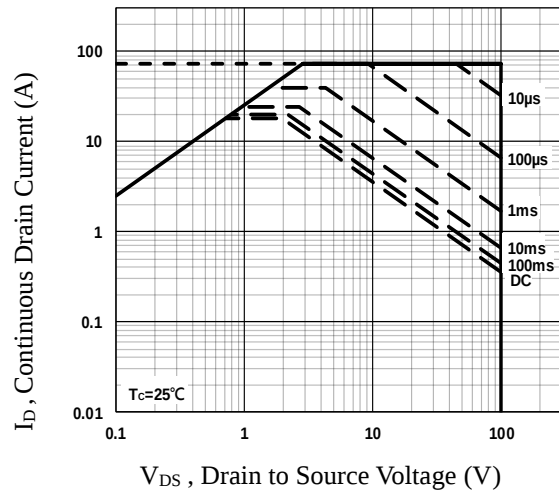
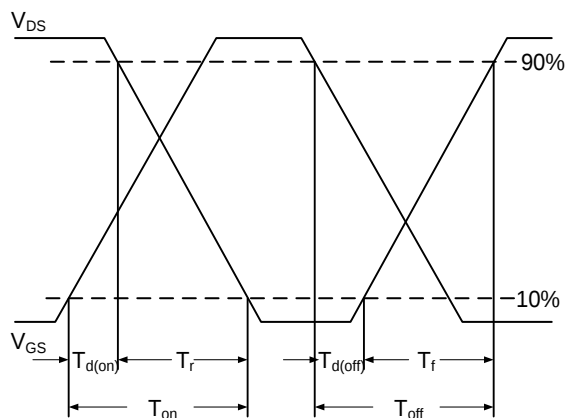
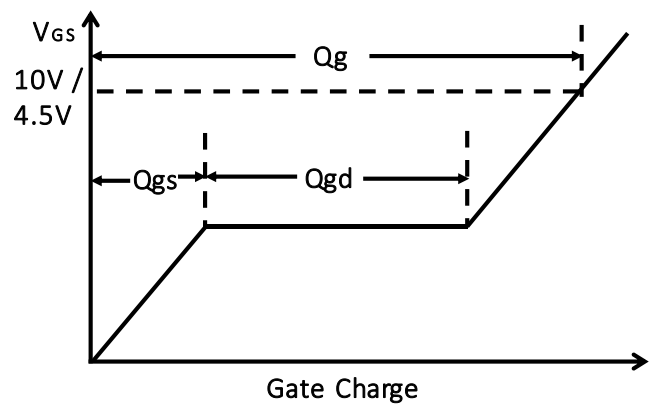
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V$, Force Current	---	---	16	A
I_{SM}	Pulsed Source Current		---	---	32	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V
T_{rr}	Reverse Recovery Time	$V_R=50V, I_S=10A$	---	40	---	ns
Q_{rr}	Reverse Recovery Charge	$di/dt=100A/\mu s, T_J=25^\circ\text{C}$	---	50	---	nC

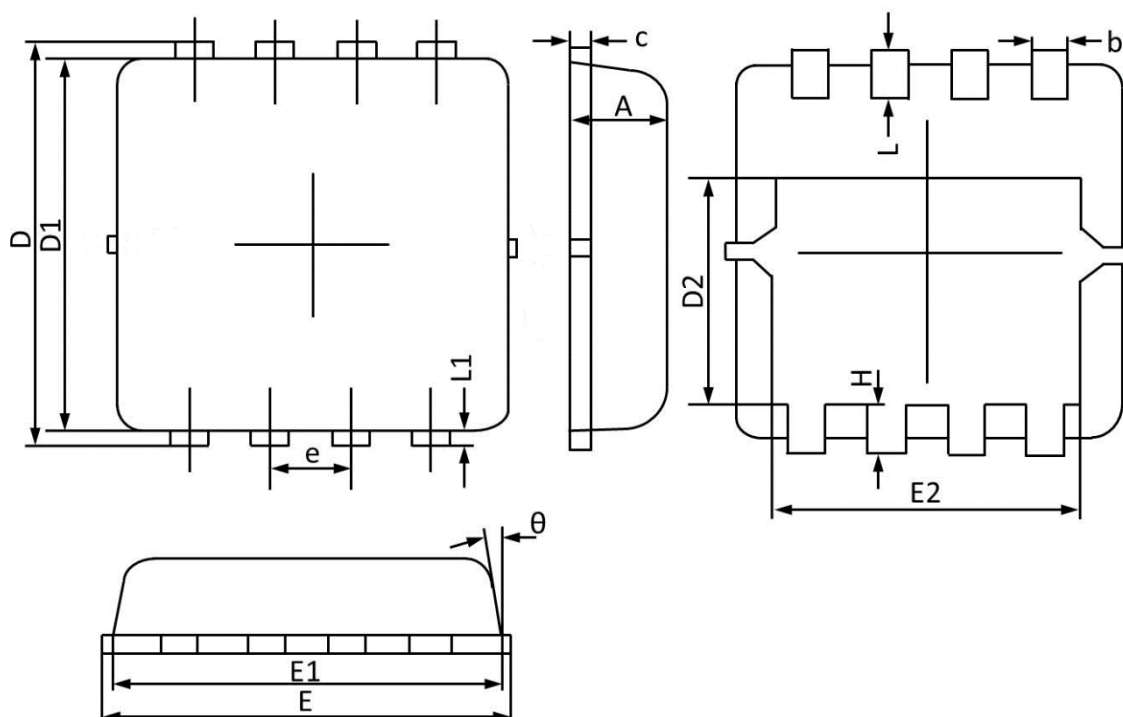
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=50V, V_{GS}=10V, L=0.1mH, I_{AS}=20A, R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.
3. Essentially independent of operating temperature.


Fig.1 Typical Output Characteristics

Fig.2 Continuous Drain Current vs. T_c

Fig.3 Normalized $R_{DS(on)}$ vs. T_J

Fig.4 Normalized V_{th} vs. T_J

Fig.5 Turn-On Resistance vs. V_{GS}

Fig.6 Turn-On Resistance vs. I_D

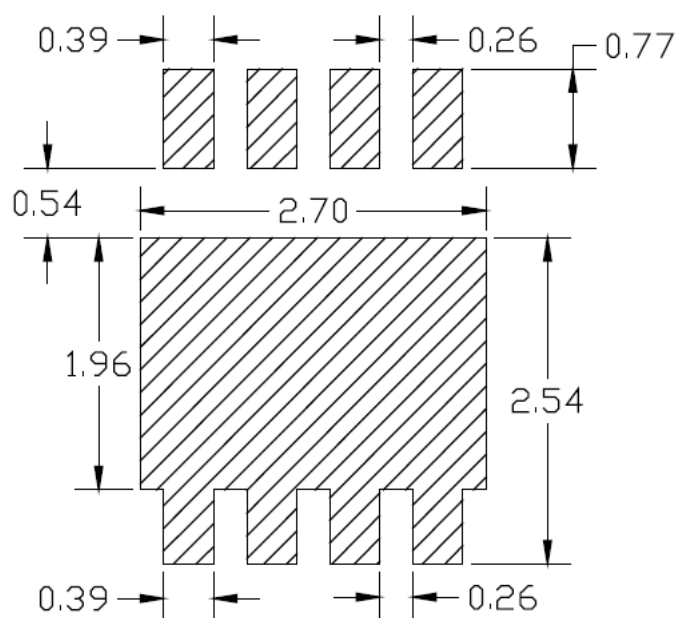

Fig.7 Capacitance Characteristics

Fig.8 Gate Charge Characteristics

Fig.9 Normalized Transient Impedance

Fig.10 Maximum Safe Operation Area

Fig.11 Switching Time Waveform

Fig.12 Gate Charge Waveform

PPAK3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.250	0.014	0.010
c	0.250	0.100	0.010	0.004
D	3.500	3.050	0.138	0.120
D1	3.200	2.900	0.126	0.114
D2	1.950	1.350	0.077	0.053
E	3.400	3.000	0.134	0.118
E1	3.300	2.900	0.130	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.750	0.300	0.030	0.012
L	0.600	0.300	0.024	0.012
L1	0.200	0.060	0.008	0.002
θ	14°	6°	14°	6°

PPAK3X3 RECOMMENDED LAND PATTERN



unit : mm